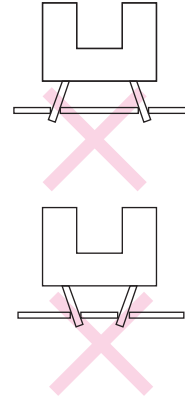


Soldering Condition

■ Mounting method

- ① When mounting on a substrate, the distance of the mounting holes on the substrate and the pitches of lead pins should be identical.
The lead pin pitch should not be shortened or widened.
- ② When a holder is used in determining position, avoid putting stress to the lead pins and take into consideration how much the holder, substrate and product can tolerate.



Caution

Be careful with thermal expansion and contraction of the material used. Expansion and contraction of the holder due to the heat from the pre-heating and soldering processes could put stress on the lead pins, resulting in broken wires.

- The recommended soldering conditions are given below.

Item	Conditions	Soldering temperature	Operation time
Solder dipping	Conducted at a distance of 1.0 mm from the resin	Preheating below 100°C (Max 30 SEC) 260°C or lower	5 seconds or shorter
Soldering iron	Conducted at a distance of 1.0 mm from the resin Wattage : 30W or lower Tip diameter : 3mm or shorter	380°C or lower	3 seconds or shorter (2times)
Reflow soldering	Reflow soldering is not permitted.		

* Use rosin-based flux only. Note that strongly acid or alkaline flux may cause corrosion.

* The surface mount devices require special attention. Please check requested time control after opening sealed bag, land pattern, the thickness of solder paste screen etc.